

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
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CORRESPONDENCE DATA															
<p>Fax Number:</p> <p>Phone: 214-651-5000</p> <p>Email: ipdocketing@haynesboone.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: HAYNES AND BOONE, LLP</p> <p>Address Line 1: 2323 VICTORY AVENUE SUITE 700</p> <p>Address Line 4: DALLAS, TEXAS 75219</p>															
ATTORNEY DOCKET NUMBER:	2010-0770/24061.2691														

NAME OF SUBMITTER:	SCOTT MATTHEWS
Signature:	/sm82918/
Date:	01/15/2014
Total Attachments: 3 source=14074435Assign#page1.tif source=14074435Assign#page2.tif source=14074435Assign#page3.tif	

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Chih-Chang Cheng | of | 3F., No. 113, Lane 19, Guanxin Road
East District, Hsinchu City 300
Taiwan, R.O.C. |
| (2) | Ruey-Hsin Liu | of | 5F-3, No. 56, University Road
Hsin-Chu, Taiwan, R.O.C. |
| (3) | Chih-Wen Yao | of | 5F., No. 19, Lane 51, Jiangong 1st Road
Hsinchu City 300, Taiwan, R.O.C. |
| (4) | Ru-Yi Su | of | No. 53, Wenming Road, Kouhu Township
Yunlin County 653, Taiwan, R.O.C. |
| (5) | Fu-Chih Yang | of | No. 7, Lane 90, Yonghe Street
Fengshan City, Kaohsiung County 830
Taiwan, R.O.C. |
| (6) | Chun Lin Tsai | of | No. 30, Alloy 28, Lane 251, Road
Tung-Chung, Hsin-Chu
Taiwan, R.O.C. |

have invented certain improvements in

HIGH VOLTAGE RESISTOR

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
X filed on November 7, 2013, and assigned application number 14/074,435; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals,

and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chih-Chang Cheng

Residence Address: 3F., No. 113, Lane 19, Guanxin Road, East District,
Hsinchu City 300, Taiwan, R.O.C.

✓ Dated: 2013.11.15

✓ Chih-Chang Cheng
Inventor Signature

Inventor Name: Ruey-Hsin Liu

Residence Address: 5F-3, No. 56, University Road, Hsin-Chu, Taiwan, R.O.C.

✓ Dated: 2013.11.15

✓ Ruey-Hsin Liu
Inventor Signature

Inventor Name: Chih-Wen Yao

Residence Address: 5F., No. 19, Lane 51, Jiangong 1st Road
Hsinchu City 300, Taiwan, R.O.C.

✓ Dated: 2013.11.15

✓ Chih-Wen Yao
Inventor Signature

Inventor Name: Ru-Yi Su

Residence Address: No. 53, Wenming Road
Kouhu Township, Yunlin County 653, Taiwan, R.O.C.

✓ Dated: 11/18, 2013

✓ Ru-Yi Su
Inventor Signature

Inventor Name: Fu-Chih Yang

Residence Address: No. 7, Lane 90, Yonghe Street
Fengshan City, Kaohsiung County 830, Taiwan, R.O.C.

✓ Dated: 11/18, 2013

✓ Fu-Chih Yang
Inventor Signature

Inventor Name: Chun Lin Tsai

Residence Address: No. 30, Alloy 28, Lane 251, Road Tung-Chung
Hsin-Chu, Taiwan, R.O.C.

✓ Dated: 11/15, 2013

✓ Chun-Lin Tsai
Inventor Signature
